

**AMENDMENTS TO THE SPECIFICATION**

Please amend the title as follows:

SLIDING COMPONENT AND METHOD FOR MANUFACTURING THE SAME

Following the title, please insert the following paragraphs:

**Cross-Reference to Prior Application**

This is a U.S. National Phase application under 35 U.S.C. §371 of International Patent Application No. PCT/JP2003/009862 filed August 4, 2003, and claims the benefit of Japanese Patent Application No. 2002-249692 filed August 28, 2002 both of which are incorporated by reference herein. The International Application was published in Japanese on March 11, 2004 as WO 2004/020129 A1 under PCT Article 21(2).

Please replace the paragraph starting from page 4, line 4 with the following amended paragraph:

--In order to attain the above objects, there is provided a method for manufacturing a sliding component according to another aspect of the present invention, including the steps of filling an iron-based material powder and a copper-based material powder in a filling portion of a mold; compacting the iron- and copper-based material powders so as to form a green compact; and sintering the green compact, wherein the copper-based material powder contains flat powder particles of copper or copper alloy; an average value of maximum projected areas of the flat powder particles is larger than that of maximum projected areas of the particles of the iron-based material powder; and the flat powder particles in the filling portion are allowed to segregate on the surface of the green compact.--

Please replace the paragraph starting from page 6, line 21 with the following amended paragraph:

--First, a method for manufacturing a sliding component according to an embodiment of the present invention will now be explained. An iron-based material powder 1, a copper-based material powder 2 and a small amount of an other material powder 3 are mixed as materials in a predetermined proportion (Step S1). For the iron-based material powder 1, a powder composed of substantially spherical and irregular particles such as atomized powder is used as shown in FIG. 2. For the copper-based material powder 2, an irregular-particle powder 2A and a flat powder particles 2B are used as shown in FIGs. 2, 3A and 3B.--